



DMTH8008SPSQ

PowerDI5060-8

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Product Summary

BV _{DSS}	Rds(on)	I _D Tc = +25°С
80V	7.8mΩ @ V _{GS} = 10V	92A

Description and Applications

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

PowerDI5060-8

- **DC-DC** Converters
- Load Switch

Features

Rated to +175°C - Ideal for High Ambient Temperature Environments

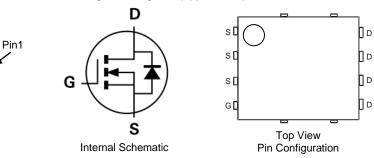
80V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET

- 100% Unclamped Inductive Switching (UIS) Test in Production -Ensures More Reliable and Robust End Application
- **High Conversion Efficiency**
- Low RDS(ON) Minimizes On State Losses
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMTH8008SPSQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

https://www.diodes.com/quality/product-definitions/

Mechanical Data

- Case: PowerDI®5060-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
 - Weight: 0.097 grams (Approximate)



Ordering Information (Note 4)

Top View

Part Number	Case	Packaging
DMTH8008SPSQ-13	PowerDI5060-8	2,500 / Tape & Reel

1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied. 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and

Lead-free. 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

) | | = Manufacturer's Marking

YYWW = Date Code Marking

YY = Year (ex: 19 = 2019)WW = Week (01 to 53)

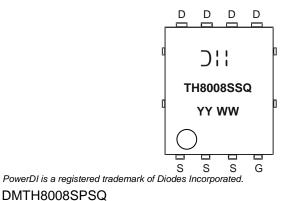
TH8008SSQ = Product Type Marking Code

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Bottom View

Marking Information

Notes:



Document number: DS40781 Rev. 3 - 2



Maximum Ratings (@Tc = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			VDSS	80	V
Gate-Source Voltage			Vgss	±20	V
Continuous Drain Current, V _{GS} = 10V (Note 7)	Steady State	Tc = +25°C T _C = +100°C	ID	92 65	А
Maximum Continuous Body Diode Forward Current (Note 7)			ls	83	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			ldм	360	A
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)			I _{SM}	360	A
Avalanche Current, L = 0.1mH (Note 8)			las	40	A
Avalanche Energy, L = 0.1mH (Note 8)			Eas	80	mJ

Thermal Characteristics (@T_C = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T _A = +25°C	PD	1.6	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{ heta JA}$	92	°C/W
Total Power Dissipation (Note 6)	T _A = +25°C	PD	3.4	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	RθJA	43	°C/W
Total Power Dissipation (Note 7)	T _C = +25°C	PD	100	W
Thermal Resistance, Junction to Case (Note 7)		R _{θJC}	1.5	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +175	°C

Electrical Characteristics (@Tc = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BVDSS	80	—	—	V	$V_{GS} = 0V, I_D = 1mA$
Zero Gate Voltage Drain Current	IDSS	_	—	1	μA	$V_{DS} = 64V, V_{GS} = 0V$
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	VGS(TH)	2	_	4	V	$V_{DS} = V_{GS}, I_D = 1mA$
Static Drain-Source On-Resistance	Descent		6.5	7.8	mΩ	Vgs = 10V, ID = 14A
	RDS(ON)	_	7.8	11	11152	$V_{GS} = 6V, I_D = 12A$
Diode Forward Voltage	Vsd	_	0.8	1.2	V	$V_{GS} = 0V, I_{S} = 14A$
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	Ciss		1950	—		$V_{DS} = 40V, V_{GS} = 0V,$ f = 1MHz
Output Capacitance	Coss	-	826	—	pF	
Reverse Transfer Capacitance	Crss	_	56	_		
Gate Resistance	Rg	_	1.7	—	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$
Total Gate Charge (V _{GS} = 6V)	Qg	_	23	—		V _{DS} = 40V, I _D = 14A
Total Gate Charge (V _{GS} = 10V)	Qg	_	34	_	nC	
Gate-Source Charge	Qgs	_	6	_	nc	
Gate-Drain Charge	Q _{gd}	_	12	_		
Turn-On Delay Time	tD(ON)	_	8	_		$V_{DD} = 40V, V_{GS} = 10V,$ $I_D = 14A, R_G = 6\Omega$
Turn-On Rise Time	tR	_	15	_		
Turn-Off Delay Time	tD(OFF)		29	—	ns	
Turn-Off Fall Time	tF		21	_	1	
Body Diode Reverse Recovery Time	t _{RR}	_	43	—	ns	
Body Diode Reverse Recovery Charge	QRR	_	49	_	nC	Is = 14A, di/dt = 100A/µs

Notes:

Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.

7. Thermal resistance from junction to soldering point (on the exposed drain pad).

8. I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25^{\circ}C$.

9. Short duration pulse test used to minimize self-heating effect.

10. Guaranteed by design. Not subject to product testing.



50.0 30 $V_{GS} = 5.0V$ 45.0 _{GS} = 6.0V 25 $V_{GS} = 8.0V$ 40.0 $V_{\rm GS} = 10V$ ID, DRAIN CURRENT (A) 35.0 I_D, DRAIN CURRENT (A) $V_{GS} = 4.5V$ 20 30.0 25.0 15 20.0 10 15.0 $V_{GS} = 4.0V$ 10.0 5 5.0 $V_{GS} = 3.5\overline{V}$ 0.0 0 0.5 1 1.5 2 2.5 3 0 V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 1. Typical Output Characteristic 0.012 0.1 $R_{\text{DS}(\text{ON})},$ DRAIN-SOURCE ON-RESISTANCE ($\Omega)$ 0.011 0.010 0.009 $V_{GS} = 6.0V$ 0.008 0.007 0.006 0.005 $V_{GS} = 10V$ 0.004 R_{DS(ON)}, 0.003 0.002 0 5 10 15 20 25 30 35 40 45 0 50 I_D, DRAIN-SOURCE CURRENT (A) Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage 0.016 2.4 R_{DS(ON)}, DRAIN-SOURCE ON-RESISTANCE $V_{GS} = 10V$ R_{DS(ON)}, DRAIN-SOURCE ON-RESISTANCE (NORMALIZED) 2.2 0.014 T_J = 175°C T_J = 150°C 2 0.012 1.8 0.01 1.6 T_J = 125℃ ĝ 0.008 1.4 T_J = 85°C 1.2 0.006 $T_J = 25^{\circ}C$ 1 0.004 0.8 T₁ = -55°C 0.002 0.6 0 0.4 20 25 0 5 10 15 30 I_D, DRAIN CURRENT (A) Figure 5. Typical On-Resistance vs. Drain Current

and Temperature

 $T_{J} = 175^{\circ}C$ T_J = 85°C = 150°C T_J = 25°C $T_{\rm J}$ 125 = -55°C 1.5 2 2.5 3 3.5 4 4.5 5 5.5 6 1 V_{GS}, GATE-SOURCE VOLTAGE (V) Figure 2. Typical Transfer Characteristic -14A $I_{D} = 12A$ 6 10 12 14 16 2 4 8 18 20 V_{GS}, GATE-SOURCE VOLTAGE (V) Figure 4. Typical Transfer Characteristic $V_{GS} = 10V, I_{D} = 14A$ $V_{GS} = 6.0V, I_{D} = 12A$ -50 -25 0 50 75 100 125 150 175 25 T_J, JUNCTION TEMPERATURE (°C)

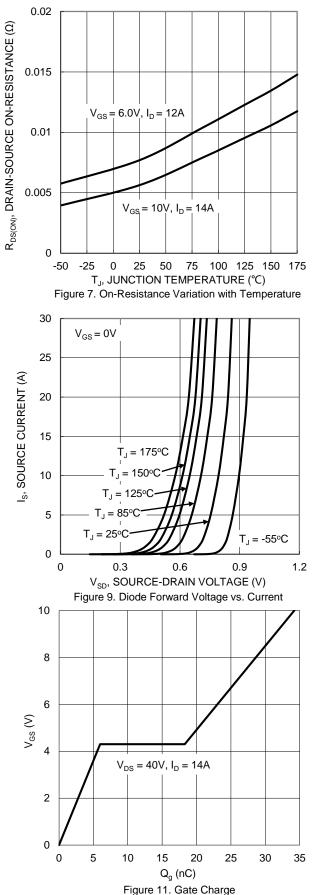
Figure 6. On-Resistance Variation with Temperature

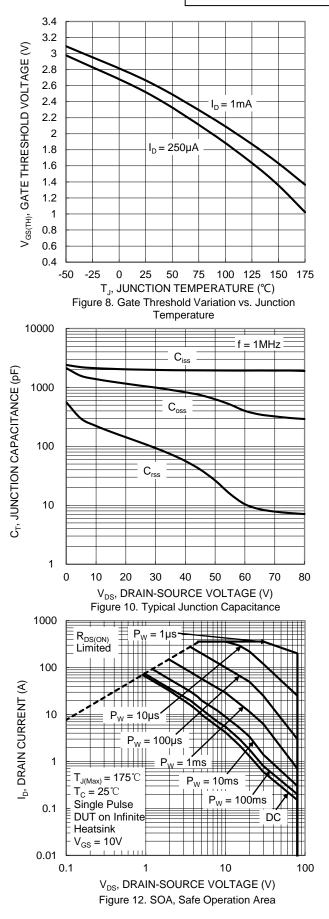
 $V_{DS} = 5.0V$

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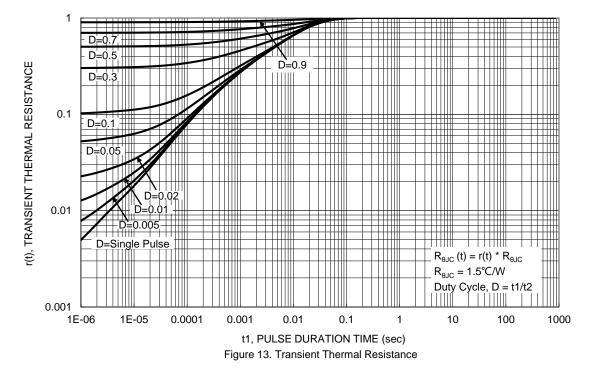


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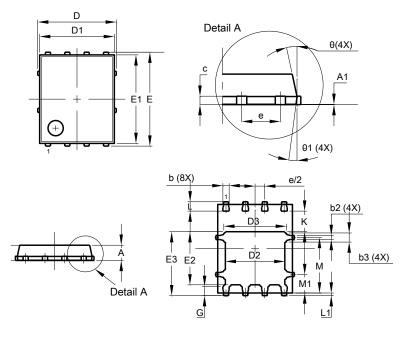




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8

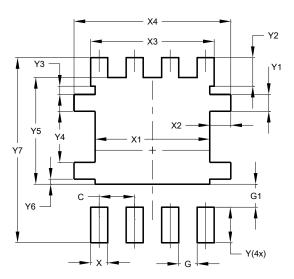


PowerDI5060-8					
Dim	Min	Max	Тур		
Α	0.90	1.10	1.00		
A1	0.00	0.05	-		
b	0.33	0.51	0.41		
b2	0.200	0.350	0.273		
b3	0.40	0.80	0.60		
С	0.230	0.330	0.277		
D	-	5.15 BSC	;		
D1	4.70	5.10	4.90		
D2	3.70	4.10	3.90		
D3	3.90	4.30	4.10		
Е	(6.15 BSC	;		
E1	5.60	6.00	5.80		
E2	3.28	3.68	3.48		
E3	3.99	4.39	4.19		
е	1.27 BSC				
G	0.51	0.71	0.61		
К	0.51	_	-		
L	0.51	0.71	0.61		
L1	0.100	0.200	0.175		
М	3.235	4.035	3.635		
M1	1.00	1.40	1.21		
Θ	10°	12°	11°		
Θ1	6°	8°	7°		
Al	All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8



Dimensions	Value (in mm)
С	1.270
G	0.660
G1	0.820
Х	0.610
X1	4.100
X2	0.755
X3	4.420
X4	5.610
Y	1.270
Y1	0.600
Y2	1.020
Y3	0.295
Y4	1.825
Y5	3.810
Y6	0.180
Y7	6.610



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